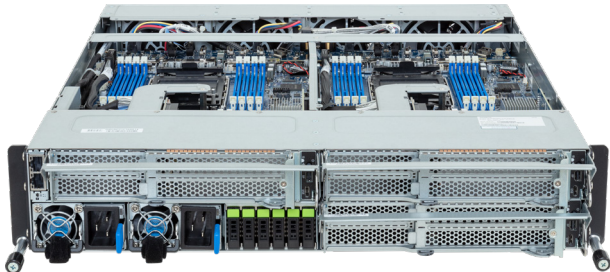


H223-S10-AAP1

High Density Server - 2U 3-Node UP 6-Bay E1.S NVMe



Features

- 2U 3-node front access server system
- 4th/5th Gen Intel® Xeon® Scalable Processors
- Intel® Xeon® CPU Max Series
- Single processor per node, LGA 4677
- 8-Channel RDIMM DDR5 per processor, 24 x DIMMs
- Dual ROM Architecture
- 2 x CMC ports
- 6 x 9.5mm E1.S Gen4 NVMe hot-swappable bays
- 3 x M.2 slots with SATA interface
- 6 x FHHL PCIe Gen5 x16 slots
- 3 x LP PCIe Gen5 x16 slots
- 3 x LP PCIe Gen5 x8 slots
- 1+1 3000W 80 PLUS Titanium redundant power supplies

Specification

Dimensions	2U 3-Node - Front access (W447.8 x H87.5 x D500 mm)	Backplane Board	Speed and bandwidth: PCIe Gen4 x4
Motherboard	MS13-HD0	TPM	1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010
CPU	4th/5th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Single processor per node	Power Supply	1+1 3000W 80 PLUS Titanium redundant power supplies AC Input: 100-240V
Socket	Total: 3 x LGA 4677	System Management	Aspeed® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
Chipset	Intel® C741 Chipset	OS Compatibility	Windows Server 2019 / 2022 RHEL 8.6 / 8.7 / 8.8 / 8.9 / 9.0 / 9.1 / 9.2 / 9.3 (x64) SLES 15 SP4 / SP5 (x64) Ubuntu 20.04.6 / 22.04 / 22.04.1 / 22.04.2 / 22.04.3 LTS (x64) VMware ESXi 7.0 Update 3i & 3o / 8.0 / 8.0 Update 1 & 2 Citrix Hypervisor 8.2 LTSR CU1
Memory	Total 24 x DIMM slots (8 x DIMM slots per node) RDIMM modules up to 96GB supported 3DS RDIMM modules up to 256GB supported Up to 5600MHz (1DPC), 4400MHz (2DPC)	System Fans	4 x 80x80x38mm (18,300rpm)
LAN	Total: 2 x CMC ports	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Video	Integrated in Aspeed AST2600 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM Management chip on CMC board: Integrated in Aspeed AST2520A2-GP	Packaging Content	1 x H223-S10, 3 x CPU heatsinks, 1 x Mini-DP to D-Sub cable, 9 x Carrier clips, 1 x L-shape Rail kit
Storage	Total: 6 x 9.5mm E1.S Gen4 NVMe hot-swappable bays	Part Numbers	Barebone package (4th/5th Gen): 6NH223S10DR000ABP1* Barebone package (4th Gen): 6NH223S10DR000AAP1* - Motherboard: 9MS13HD0UR-000 - L-shape Rail kit: 25HB2-A86105-K0R - CPU heatsink: 25ST1-453207-C1R - Mini-DP to D-Sub cable: 25CRN-200801-K1R - Power Supply: 25EP0-23000F-G1S
RAID	N/A		
Expansion Slots	Total: 6 x FHHL PCIe Gen5 x16 slots 3 x LP PCIe Gen5 x16 slots 3 x LP PCIe Gen5 x8 slots 3 x M.2 slots (M-key, SATA, supports 2242/2260/2280/22110)		
Front I/O	Total: 3 x USB 3.2 Gen1 Type-C, 3 x Mini-DP, 2 x CMC ports		



Learn more about GIGABYTE server, visit <https://www.gigacomputing.com>

Designed by



* All specifications are subject to change without notice. Please visit our website for the latest information.
* Intel, the Intel logo, Xeon, and other Intel marks are trademarks of Intel Corporation or its subsidiaries.
* All other brands, logos and names are property of their respective owners.

© 2024 Giga Computing Technology Co., Ltd. All rights reserved.